



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20231004001.1**

**Qualification of RFAB as an additional Fab site option for select HPA07 devices  
Change Notification / Sample Request**

**Date:** October 05, 2023  
**To:** PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team  
SC Business Services

**20231004001.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA2376AID	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20231004001.1	<b>PCN Date:</b>	October 05, 2023																		
<b>Title:</b>	Qualification of RFAB as an additional Fab site option for select HPA07 devices																				
<b>Customer Contact:</b>	Change Management team	<b>Dept:</b>	Quality Services																		
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Jan 5, 2024	<b>Sample requests accepted until:</b>	November 5, 2023*																		
<b>*Sample requests received after November 5, 2023 will not be supported.</b>																					
<b>Change Type:</b>																					
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material																			
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process																			
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/> Wafer Fab Site																			
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/> Wafer Fab Material																			
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process																			
<b>PCN Details</b>																					
<b>Description of Change:</b>																					
Texas Instruments is pleased to announce the addition of RFAB as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.																					
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">New Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>New Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>AIZU</td> <td>HPA07</td> <td>200mm</td> <td>RFAB</td> <td>HPA07</td> <td>300mm</td> </tr> </tbody> </table>			Current Fab Site			New Fab Site			Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter	AIZU	HPA07	200mm	RFAB	HPA07	300mm	
Current Fab Site			New Fab Site																		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter																
AIZU	HPA07	200mm	RFAB	HPA07	300mm																
Qual details are provided in the Qual Data Section.																					
<b>Reason for Change:</b>																					
Continuity of supply																					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																					
None																					
<b>Changes to product identification resulting from this PCN:</b>																					
<b>Fab Site Information:</b>																					
<table border="1"> <thead> <tr> <th>Chip Site</th> <th>Chip Site Origin Code (20L)</th> <th>Chip Site Country Code (21L)</th> <th>Chip Site City</th> </tr> </thead> <tbody> <tr> <td>AIZU</td> <td>CU2</td> <td>JPN</td> <td>Aizuwakamatsu-shi</td> </tr> <tr> <td><b>RFAB</b></td> <td><b>RFB</b></td> <td><b>USA</b></td> <td><b>Richardson</b></td> </tr> </tbody> </table>	Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City	AIZU	CU2	JPN	Aizuwakamatsu-shi	<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>									
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Sample product shipping label (not actual product label)																					
<b>Product Affected:</b>																					
OPA2376AID	OPA2376AIDR	OPA2377AIDGKT	TLV2376IDGKT																		
OPA2376AIDGKR	OPA2377AID	OPA2377AIDR	TLV2376IDR																		
OPA2376AIDGKT	OPA2377AIDGKR	TLV2376IDGKR																			

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">OPA2376AIDGKR</a>	Qual Device: <a href="#">OPA2376AIDR</a>	Qual Device: <a href="#">OPA2377AID</a>	QBS Process Reference: <a href="#">CD3232A1YFFR</a>	QBS Process Reference: <a href="#">CD3232A1YFFR</a>	QBS Process Reference: <a href="#">AMC7836IPAP</a>	QBS Process Reference: <a href="#">DRV401AIRGWR</a>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0	3/231/0	-	-
HTOL	B1	Life Test	140C	480 Hours	-	-	-	1/77/0	2/154/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	1/77/0	2/154/0
ELFR	B2	ELFR	125C	48 Hours	-	-	-	1/1000/0	2/2000/0	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	1/3/0	-	-	1/3/0	2/6/0
ESD	E2	ESD CDM	-	200 Volts	-	-	-	-	3/9/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	2/6/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	1/3/0	2/6/0	3/9/0	-	2/6/0

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">OPA2376AIDGKR</a>	Qual Device: <a href="#">OPA2376AIDR</a>	Qual Device: <a href="#">OPA2377AID</a>	QBS Process Reference: <a href="#">CD3232A1YFFR</a>	QBS Process Reference: <a href="#">CD3232A1YFFR</a>	QBS Process Reference: <a href="#">AMC7836IPAP</a>	QBS Process Reference: <a href="#">DRV401AIRGWR</a>
ESD	E2	ESD HBM	-	2500 Volts	-	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	4000 Volts	-	-	1/3/0	-	-	-	-
LU	E4	LU	Per JESD78	-	-	-	-	2/6/0	3/9/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/3/0	-	-	1/3/0	2/6/0 <sup>2,3</sup>
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30	1/30/0	-	1/30/0	1/30/0	1/30/0	1/30/0
FTY	E6	Final Test Yield	-	-	1/Pass	1/Pass	1/Pass	-	-	-	-

- QBS: Qual By Similarity
- Qual Device OPA2376AIDGKR is qualified at MSL2 260C
- Qual Device OPA2376AIDR is qualified at MSL2 260C
- Qual Device OPA2377AID is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2305-068

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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